

# NEW PRODUCT

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## TSF-6592HF



## TSF-6592HF IS A NO-CLEAN TACKY SOLDERING FLUX DESIGNED AS A LEAD-FREE SOLUTION FOR AN ARRAY OF LEAD-FREE INTERCONNECT APPLICATIONS FEATURING:

- Compatible with lead-free alloys such as SnAg, SnCu, SnAgCu, SnAgBi
- Reflowable with peak temperatures up to 270°C
- Reflowable in air and nitrogen
- Low voiding
- Bright shiny soldered joints with clear residues
- Aggressive flux on various substrates such as OSP-Cu, immersion finishes and ENIG
- Clear non-tacky residues
- Classified as ROL0 per J-STD-004A
- High tack to minimize skewing of components
- Stencil life of 8+ hours (process dependent)
- Compliant to Bellcore GR-78